



THE DATASHEET OF CY74FCT273ATSOCT



CY54FCT273T, CY74FCT273T 8-BIT REGISTERS

SCCS020A – MARCH 1995 – REVISED OCTOBER 2001

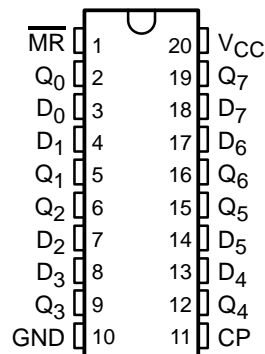
- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT273T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT273T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

description

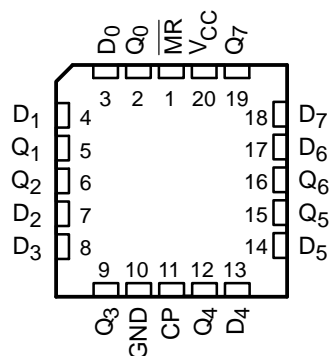
The 'FCT273T devices consist of eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered-clock (CP) and master-reset (\overline{MR}) inputs load and reset all flip-flops simultaneously. These devices are edge-triggered registers. The state of each D input (one setup time before the low-to-high clock transition) is transferred to the corresponding flip-flop's Q output. All outputs are forced low by a low logic level on the \overline{MR} input.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

CY54FCT273T . . . D PACKAGE
CY74FCT273T . . . Q OR SO PACKAGE
(TOP VIEW)



CY54FCT273T . . . L PACKAGE
(TOP VIEW)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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CY54FCT273T, CY74FCT273T 8-BIT REGISTERS

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ORDERING INFORMATION

| T _A | PACKAGE† | | SPEED (ns) | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|---------------|---------------|-----------------|-----------------------|------------------|
| -40°C to 85°C | QSOP – Q | Tape and reel | 5.8 | CY74FCT273CTQCT | FCT273C |
| | SOIC – SO | Tube | 5.8 | CY74FCT273CTSOC | FCT273C |
| | | Tape and reel | 5.8 | CY74FCT273CTSOCT | |
| | QSOP – Q | Tape and reel | 7.2 | CY74FCT273ATQCT | FCT273A |
| | | SOIC – SO | Tube | 7.2 | CY74FCT273ATSOC |
| | Tape and reel | | 7.2 | CY74FCT273ATSOCT | |
| -55°C to 125°C | QSOP – Q | Tape and reel | 13 | CY74FCT273TQCT | FCT273 |
| | SOIC – SO | Tube | 13 | CY74FCT273TSOC | FCT273 |
| | | Tape and reel | 13 | CY74FCT273TSOCT | |
| LCC – L | Tube | 8.3 | CY54FCT273ATLMB | | |

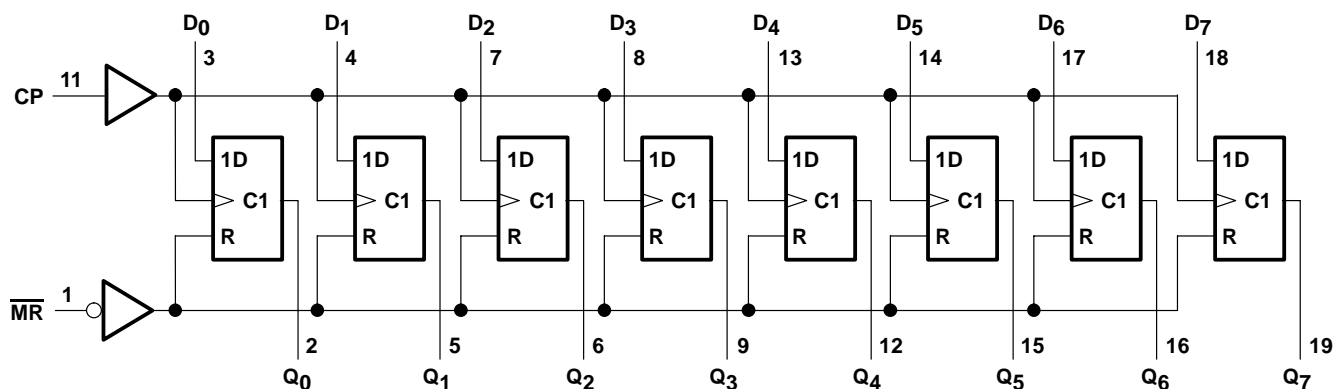
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

| INPUTS | | | OUTPUT Q | OPERATING MODE |
|-----------------|----|---|----------|----------------|
| \overline{MR} | CP | D | | |
| L | X | X | L | Reset (clear) |
| H | ↑ | h | H | Load '1' |
| H | ↑ | l | L | Load '0' |

H = High logic level steady state, h = High logic level one setup time prior to low-to-high clock transition, L = Low logic level steady state, l = Low logic level one setup time prior to the low-to-high transition, X = Don't care, ↑ = Low-to-high clock transition

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|----------------|
| Supply voltage range to ground potential | –0.5 V to 7 V |
| DC input voltage range | –0.5 V to 7 V |
| DC output voltage range | –0.5 V to 7 V |
| DC output current (maximum sink current/pin) | 120 mA |
| Package thermal impedance, θ_{JA} (see Note 1): Q package | 68°C/W |
| SO package | 58°C/W |
| Ambient temperature range with power applied, T_A | –65°C to 135°C |
| Storage temperature range, T_{stg} | –65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

| | CY54FCT273T | | | CY74FCT273T | | | UNIT |
|--------------------------------------|-------------|-----|-----|-------------|-----|------|------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{CC} Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| V_{IH} High-level input voltage | 2 | | | 2 | | | V |
| V_{IL} Low-level input voltage | 0.8 | | | 0.8 | | | V |
| I_{OH} High-level output current | –12 | | | –32 | | | mA |
| I_{OL} Low-level output current | 32 | | | 64 | | | mA |
| T_A Operating free-air temperature | –55 | | 125 | –40 | | 85 | °C |

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

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8-BIT REGISTERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | CY54FCT273T | | | CY74FCT273T | | | UNIT |
|-------------------|--|--------------------------|------|------|-------------|------|------|------|
| | | MIN | TYP† | MAX | MIN | TYP† | MAX | |
| V _{IK} | V _{CC} = 4.5 V, I _{IN} = -18 mA | -0.7 | -1.2 | | | | | V |
| | V _{CC} = 4.75 V, I _{IN} = -18 mA | | | | -0.7 | -1.2 | | |
| V _{OH} | V _{CC} = 4.5 V, I _{OH} = -12 mA | 2.4 | 3.3 | | | | | V |
| | V _{CC} = 4.75 V | I _{OH} = -32 mA | | | 2 | | | |
| | | I _{OH} = -15 mA | | | 2.4 | 3.3 | | |
| V _{OL} | V _{CC} = 4.5 V, I _{OL} = 32 mA | 0.3 | 0.55 | | | | | V |
| | V _{CC} = 4.75 V, I _{OL} = 64 mA | | | | 0.3 | 0.55 | | |
| V _{hys} | All inputs | 0.2 | | | 0.2 | | | V |
| I _I | V _{CC} = 5.5 V, V _{IN} = V _{CC} | | | 5 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = V _{CC} | | | | | 5 | | |
| I _{IH} | V _{CC} = 5.5 V, V _{IN} = 2.7 V | | | ±1 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = 2.7 V | | | | | ±1 | | |
| I _{IL} | V _{CC} = 5.5 V, V _{IN} = 0.5 V | | | ±1 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = 0.5 V | | | | | ±1 | | |
| I _{off} | V _{CC} = 0 V, V _{OUT} = 4.5 V | | | ±1 | | | ±1 | μA |
| I _{OS} ‡ | V _{CC} = 5.5 V, V _{OUT} = 0 V | -60 | -120 | -225 | | | | mA |
| | V _{CC} = 5.25 V, V _{OUT} = 0 V | | | | -60 | -120 | -225 | |
| I _{CC} | V _{CC} = 5.5 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} - 0.2 V | 0.1 | 0.2 | | | | | mA |
| | V _{CC} = 5.25 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} - 0.2 V | | | | 0.1 | 0.2 | | |
| ΔI _{CC} | V _{CC} = 5.5 V, V _{IN} = 3.4 V§, f ₁ = 0, Outputs open | 0.5 | 2 | | | | | mA |
| | V _{CC} = 5.25 V, V _{IN} = 3.4 V§, f ₁ = 0, Outputs open | | | | 0.5 | 2 | | |

† Typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

| PARAMETER | TEST CONDITIONS | | CY54FCT273T | | CY74FCT273T | | UNIT | |
|----------------------|--|---|--|------|------------------|------|------------|------------------|
| | | | MIN | TYP† | MAX | MIN | | TYP† |
| I_{CCD}^{\ddagger} | $V_{CC} = 5.5$ V, Outputs open, One bit switching at 50% duty cycle, $\overline{MR} = V_{CC}$, $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V | | 0.06 | 0.12 | | | mA/ MHz | |
| | $V_{CC} = 5.25$ V, Outputs open, One bit switching at 50% duty cycle, $\overline{MR} = V_{CC}$, $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V | | | | 0.06 | 0.12 | | |
| $I_{C}^{\#}$ | $V_{CC} = 5.5$ V, $f_0 = 10$ MHz, Outputs open, $MR = V_{CC}$ | One bit switching at $f_1 = 2.5$ MHz at 50% duty cycle | $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V | 0.7 | 1.4 | | mA | |
| | | | $V_{IN} = 3.4$ V or GND | 1.2 | 3.4 | | | |
| | | Eight bits switching at $f_1 = 2.5$ MHz at 50% duty cycle | $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V | 1.6 | 3.2 \parallel | | | |
| | | | $V_{IN} = 3.4$ V or GND | 3.9 | 12.2 \parallel | | | |
| | $V_{CC} = 5.25$ V, $f_0 = 10$ MHz, Outputs open, $MR = V_{CC}$ | One bit switching at $f_1 = 5$ MHz at 50% duty cycle | $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V | | | 0.7 | | 1.4 |
| | | | $V_{IN} = 3.4$ V or GND | | | 1.2 | | 3.4 |
| | | Eight bits switching at $f_1 = 5$ MHz at 50% duty cycle | $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V | | | 1.6 | | 3.2 \parallel |
| | | | $V_{IN} = 3.4$ V or GND | | | 3.9 | | 12.2 \parallel |
| C_i | | | 5 | 10 | 5 | 10 | pF | |
| C_o | | | 9 | 12 | 9 | 12 | pF | |

† Typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

\ddagger This parameter is derived for use in total power-supply calculations.

$$\# I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4$ V)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

\parallel Values for these conditions are examples of the I_{CC} formula.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

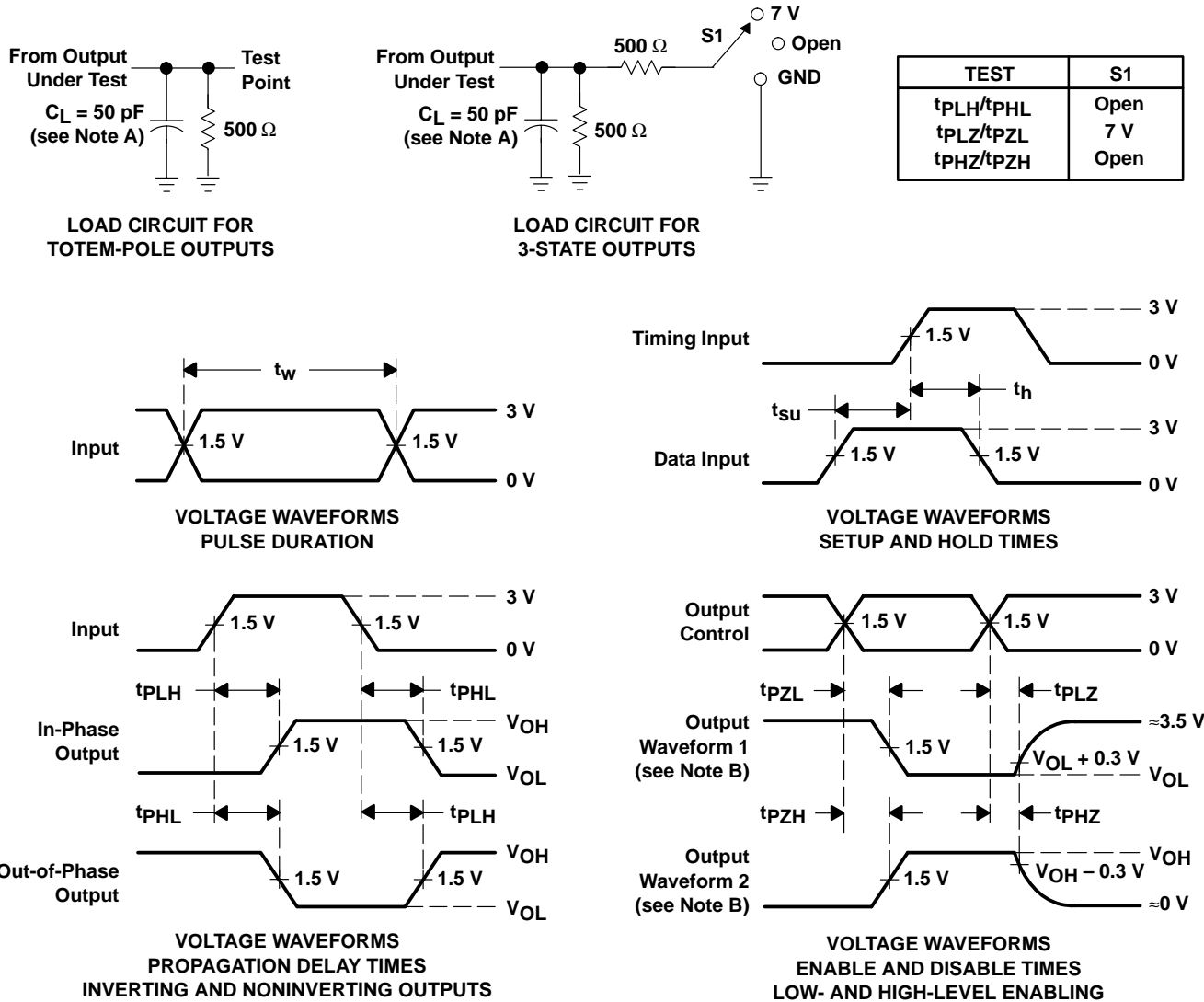
| | | | CY74FCT273T | | CY54FCT273AT | | CY74FCT273AT | | CY74FCT273CT | | UNIT |
|------------------|-----------------------------|----------------------------------|-------------|-----|--------------|-----|--------------|-----|--------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _w | Pulse duration, high or low | CP | 6 | | 6 | | 6 | | 6 | | ns |
| | | $\overline{\text{MR}}$ | 6 | | 6 | | 6 | | 6 | | |
| t _{su} | Setup time, high or low | D before CP↑ | 2 | | 2 | | 2 | | 2 | | ns |
| t _h | Hold time, high or low | D after CP↑ | 1.5 | | 1.5 | | 1.5 | | 1.5 | | ns |
| t _{rec} | Recovery time | $\overline{\text{MR}}$ after CP↑ | 2 | | 2.5 | | 2 | | 2 | | ns |

switching characteristics over operating free-air temperature range (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | CY74FCT273T | | CY54FCT273AT | | CY74FCT273AT | | CY74FCT273CT | | UNIT |
|------------------|------------------------|-------------|-------------|-----|--------------|-----|--------------|-----|--------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | CP | Q | 2 | 13 | 2 | 8.3 | 2 | 7.2 | 2 | 5.8 | ns |
| t _{PHL} | | | 2 | 13 | 2 | 8.3 | 2 | 7.2 | 2 | 5.8 | |
| t _{PLH} | $\overline{\text{MR}}$ | Q | 2 | 13 | 2 | 8.3 | 2 | 7.2 | 2 | 6.1 | ns |
| t _{PHL} | | | 2 | 13 | 2 | 8.3 | 2 | 7.2 | 2 | 6.1 | |



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|--|-------------------------|
| 5962-9221503M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-9221503M2A CY54FCT 273ATLMB | Samples |
| 5962-9221503MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9221503MR A | Samples |
| CY54FCT273ATLMB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-9221503M2A CY54FCT 273ATLMB | Samples |
| CY74FCT273ATQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | FCT273A | Samples |
| CY74FCT273ATSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT273A | Samples |
| CY74FCT273ATSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT273A | Samples |
| CY74FCT273CTQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | FCT273C | Samples |
| CY74FCT273CTSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT273C | Samples |
| CY74FCT273TQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | FCT273 | Samples |
| CY74FCT273TSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT273 | Samples |
| CY74FCT273TSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT273 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CY74FCT273ATQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT273ATSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CY74FCT273CTQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT273TQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT273TSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CY74FCT273ATQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT273ATSOCT | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT273CTQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT273TQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT273TSOCT | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |

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